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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Serial No.09/730,335
Filing Date December 4, 2000
Inventor Charles H. Dennison
Assignee Micron Technology, Inc.
Group Art Unit2811
ExaminerOri Nadav
Attorney Docket No.MI22-1577
Title Field Effect Transistors and Integrated Circuitry

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT


References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. Copies of the cited art are included. No admission is made regarding whether all the submitted references are prior art.

Respectfully submitted,

Dated: 8-18-03

By:


Mark S. Matkin
Reg. No. 32,268

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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1577SERIAL NO.
09/730,335LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)

APPLICANT: Charles H. Dennison

FILING DATE
December 4, 2000GROUP
2811

U.S. PATENT DOCUMENTS

Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
	AA	5,696,017	12/9/97	Ueno			
	AB	6,357,909 B1	3/25/03	Lin, et al.			
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AJ							
	AK							
	AL							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	AM		J. Nulman, B. Cohen, and K. Ngan, "Titanium Silicide and Titanium Nitride Layers Formed in an integrated Multichamber System", Proc. VMIC Conference (1991), pp. 312-315.
	AN		William C. O'Mara, Robert B. Herring, and Lee p. Hunt, "Handbook of Semiconductor Silicon Technology", Noyes Publ., Norwich, New York (1990), p. 684.
EXAMINER			DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.